

To: Technology Center: 2815
Facsimile Number: 703-872-9306

Total Pages Sent: 12

From: Rose A. Keagy
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 972-917-4761

RECEIVED
CENTRAL FAX CENTER
AUG 30 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Andrew Marshall

Serial No.: 10/007,332

Filed: 8-Nov-01

For: Thermal Coupling of Matched SOI Device Bodies

TI-31484

Art Unit: 2815

Examiner: Warren, M.E.

Conf. No.: 3238

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:


Robin E. Barnum

August 30, 2004
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT <u>116 (11 Pages)</u>
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT <u>(# Page)</u>
<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL (# Pages)
<input type="checkbox"/> ASSIGNMENT (# Pages)	<input type="checkbox"/> APPEAL <u>(# Pages)</u>
<input type="checkbox"/> FORMAL DRAWINGS	<input type="checkbox"/> ISSUE FEE (# Pages)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (IN TRIPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APPN (# Pages)	
<input type="checkbox"/> DIVISIONAL APPN	
NAME OF INVENTOR(S): Andrew Marshall	
TITLE OF INVENTION: Thermal Coupling of Matched SOI Device Bodies	
TI FILE NO.: TI-31484	DEPOSIT ACCT. NO.: 20-0668
FAXED: 8/30/04 DUE: 9/26/04 ATTY/SEC'Y: RAK/reb	RECEIPT DATE & SERIAL NO.: Serial No.: 10/007,332 Filing Date: November 8, 2001

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265

RECEIVED
CENTRAL FAX CENTER
AUG 30 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Andrew Marshall

Docket No.: TI-31484

Serial No.: 10/007,332

Art Unit: 2815

Filed: 11/08/01

Examiner: Warren, M. E.

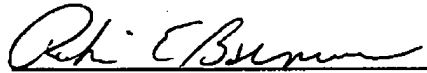
Title: Thermal Coupling of Matched SOI Device Bodies

REPLY UNDER 37 C.F.R. §1.116 – EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800

August 30, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATION OF FAX TRANSMITTAL
I hereby certify that the above correspondence is being facsimile
transmitted to the Patent and Trademark Office on August 30, 2004.


Robin E. Barnum

Dear Sir:

In response to the Office Action, dated 07/26/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.